

ABSTRACT

[0044] A device for the side-specific cleaning of a microelectronic workpiece having a front side, a back side, and an edge includes a chamber, a fixture within the chamber that is adapted to hold one or more microelectronic workpieces. At least one transducer is located within the chamber and preferably adjacent to the edge of the microelectronic workpiece. The method includes the steps of immersing the front side, back side, and edge of the microelectronic workpiece in a first processing fluid while preferably rotating the microelectronic workpiece. The microelectronic workpiece is then rinsed and dried and immersed in a second processing fluid such that the back side and edge of the microelectronic workpiece are immersed in the second processing fluid, while preferably rotating the microelectronic workpiece, without exposing the front surface of the microelectronic workpiece to the second processing fluid. Vibrational energy, preferably in the form of megasonics, is introduced during at least one of the immersions steps.